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RG128128B-FHW-V

SPECIFICATION

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

ISSUED DATE:



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1. Revision History

DATE	VERSION	REVISED PAGE NO.	Note
2010/5/4 2012/09/19	1 2	43	First issue Add Recommendable storage



2. General Specification

The Features is described as follow:

■ Module dimension: 72.5×69.9×10.0MAX) mm3

■ View area: 50.0×49.0 mm²

Active area: 44.77×44.77 mm²

■ Number of Dots: 128 x 128

■ Dot size: 0.32×0.32 mm²

■ Dot pitch: 0.35×0.35 mm²

■ LCD type: FSTN Positive, Transflective

■ Duty: 1/128

■ View direction: 6 o'clock

■ Backlight: LED, White



3. Module Coding System

R	G	128128	В	-	F	Н	W	-	٧
1	2	3	4	-	5	6	7	-	8

Item		Description	on						
1	R: Raystar C								
2	Display	C: Character Type,							
	Display	G: Graphic Type							
3		s: 128 x128 Dots							
4	Serials code	I =							
		P: TN Positive, Gray							
		N: TN Negative,							
		G: STN Positive, Gray							
5	LCD	Y: STN Positive, Yellow Gr	een						
		B: STN Negative, Blue							
		F: FSTN Positive							
		T: FSTN Negative							
		A: Reflective, N.T, 6:00	K: Transflective, W.T,12:00						
	Polarizer	D: Reflective, N.T, 12:00	1 : Transflective, U.T,6:00						
	Type,	G: Reflective, W. T, 6:00	4: Transflective, U.T.12:00						
	T	J: Reflective, W. T, 12:00	C: Transmissive, N.T,6:00						
6	Temperature range,	0 : Reflective, U. T, 6:00	F: Transmissive, N.T,12:00						
	range,	3: Reflective, U. T, 12:00	I: Transmissive, W. T, 6:00						
	View	B: Transflective, N.T,6:00	L: Transmissive, W.T,12:00						
	direction	E: Transflective, N.T.12:00	2: Transmissive, U. T, 6:00						
		H:Transflective, W.T,6:00	5: Transmissive, U.T,12:00						
		N : Without backlight	Y: LED, Yellow Green						
		P: EL, Blue green	A: LED, Amber						
7	Backlight	T: EL, Green	W: LED, White						
		D: EL, White	O: LED, Orange						
		F: CCFL, White	G: LED, Green						
8	Special code	V: Build in Negative Voltage							

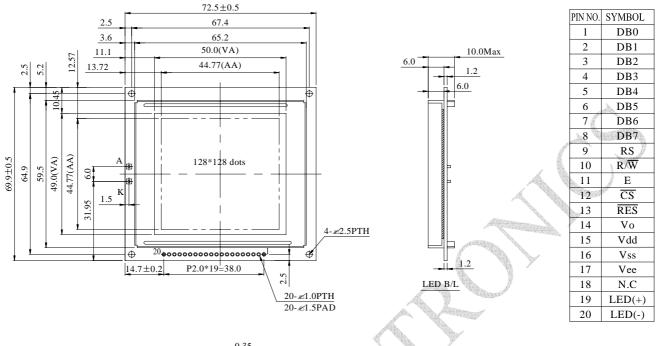


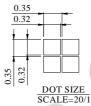
4. Interface Pin Function

Pin No.	Symbol	Level	Description
1	DB0	H/L	Data bus line
2	DB1	H/L	Data bus line
3	DB2	H/L	Data bus line
4	DB3	H/L	Data bus line
5	DB4	H/L	Data bus line
6	DB5	H/L	Data bus line
7	DB6	H/L	Data bus line
8	DB7	H/L	Data bus line
9	RS	H/L	H:Instruction,L:Data
10	R/W	H/L	H : read , L : write
11	Е	H/L	Enable
12	CS	Ĺ	Chip enable active " L "
13	RES		Reset active " L "
14	Vo		Power supply for LCD
15	Vdd		Power supply for logic circuit
16	V_{SS}		Ground
17	Vee		Negative voltage output
18	NC		No connection
19	LED(+)		LED +
20	LED(-)		LED-

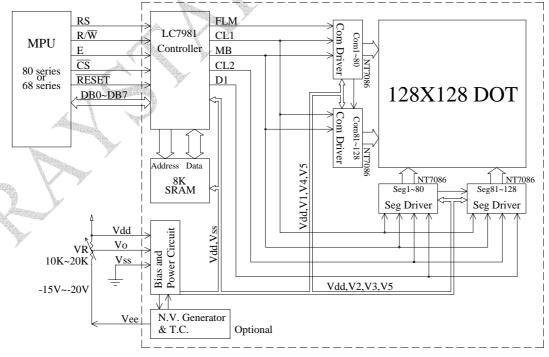


5. Outline Dimension & Block Diagram





The non-specified tolerance of dimension is ± 0.3 mm.



External contrast adjustment.



6. Display Control Instruction

The LCM has built-in a LC7981 LSI Controller, it stores display data sent from the 8 bit microcomputer in the display RAM attached externally and generates dot matrix LC drive signal.

The LC7981 has two modes-the graphic mode, in which each bit of data from the external RAM either lights or doesn't light—a dot in the LCD, and the character mode in which character codes stored in the external RAM generate dot patterns through the built-in character-generator ROM (CGROM)

below is its block diagram

Description of each block

Register

The LC7981 has 5 types of registers-the instruction register, data input register, data output register, dot register, and mode control register.

The instruction register stores such instruction codes as the start address, cursor address specification, etc. It consists of 4 bits, and the lower 4 bits of the data bus, DB0 to DB3, are written into it.

The data input register temporarily stores data to be written into the external RAM, dot register, and mode control register. It consists of 8 bits.

The data output register temporarily stores data to be read from external RAM, and consists of 8 bits. What the cursor address is written into the cursor address counter via the data input register and the memory read instruction is set in the instruction register, data in external RAM is read into the data output register by internal operation. With the next instruction, the MPU reads the data output register, and completes data transfer to the MPU.

The dot register stores dot information such as the character pitch, the number of vertical dots, etc. Data sent from the MPU is written into the dot register via the data input register.

The mode control register stores LCD status information such as display on/off and cursor on/off/blink. It consists of 6 bits. Data sent from the MPU is written into this register via the data input register.

Busy flag

When the Busy flag is "1", the LC7981 is operating internally. At this time, the next instruction cannot be accepted. The Busy flag is output to DB7 when RS=1, RW=1. The next instruction must be written after ensuring that the Busy flag is "0". When the maximum value of the read cycle time or write cycle time has been passed after the execution of the preceding data read instruction or data write instruction, the next instruction can be executed without checking the Busy flag.



Character generator ROM

The character generator ROM has a total of 7360 bits and stores data on 192 kinds of characters. Character codes from the external RAM and row codes from the row address counter are added to address signals, and ROM outputs 5-bit dot data. There are 192 kinds of character fonts, of which 160 are 5×7 and 32 are 5×11. With extended ROM, character fonts can be increased to 256 kinds sized 8×16.

Cursor address counter

The cursor address counter is a 16-bit counter which can be preset by instruction.. When data is read from or written into external RAM (i. e., read/write of display dot data or character codes), the counter retains the addresses. The value indicated on the cursor address counter is automatically incremented by 1 when instructions to read/write display data and to perform bit set/clear are issued.

Cursor signal generator

In the character mode, the cursor can be displayed by means of instructions. The cursor is generated automatically when the cursor address counter and the row address counter reach the specified value.

Display control instruction

Display is controlled by writing data into the instruction register and 13 data registers. The instruction register and the data register are distinguished by the RS signal. First, write 4-bit data in the instruction register when RS=1, then specify the code of the data register. Next, with RS=0, write 8-bit data in the data register, which executes the specified instruction.

A new instruction cannot be accepted while an old instruction is being executed. As the Busy flag is set under this condition, write an instruction only after reading the Busy flag and making sure that it is 0.

However, the next instruction can be executed without checking the Busy flag when the maximum read cycle time or the write cycle time has been exceeded after execution of the previous data read instruction or the data write instruction. The Busy flag does not change when data is written into the instruction register (RS=1). Therefore, the Busy flag need not be checked immediately after writing data into the instruction register.

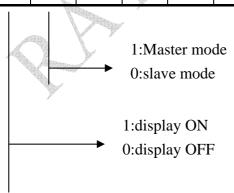


1)Mode control

Write code "00H" (in hexadecimal notation) in the instruction register and specify the mode control register.

Register		R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg.		0	1	0	0	0	0	0	0	0	0
Mode	control	0	0	0	0	MODE Data					
Reg.										A	

								15),
DB5	DB4	DB3	DB2	DB1	DB0-	Cursor/blink	CG	Graphic/character display
		0	0			Cursor OFF	(D	
		0	1			Cursor ON	90	
		1	0		0	Cursor OFF	Built-in	7
		4	4			character blink	Bu	
		1	1	0		Cursor blink		Character display
1/0 1/0	1/0	1/0 0 0	U		Cursor OFF	Ŋ	Character display	
		0	1		- A	Cursor ON	0	
		4	0			Cursor OFF	External CG	
		1	0			character blink	xte	
		1	1			Cursor blink	Ξ	
		0	0	1	0		> <	Graphic mode
Display ON/OFF	Master/slave	Blink	Cursor	Mode	External/ Built in CG			





2)Setting the character pitch

Register		R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg.		0	1	0	0	0	0	0	0	0	1
Character p	itch	0	0	(Vp-1) Binary			0	(Нр	-1) Bir	nary	
Reg.											

Vp is the number of vertical dots per character. Determine Vp with the pitch between two vertically placed characters taken into consideration. This value is meaningful only in the character display mode: It is invalid in the graphic mode.

In character mode. Hp indicates the number of horizontal dots per character, from the leftmost part of one character to the leftmost part of the next. In the graphic mode, Hp indicates how many bits (or dots) from RAM appear in a 1-byte display.

Hp must take one of the following three values.

Нр	DB2	DB1	DB0	
6	1	0	1	Horizontal character pitch 6
7	1	1	0	Horizontal character pitch 7
8	1	1	1	Horizontal character pitch 8

3)Setting the number of characters

			9858395	OMES, D						
Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg.	0	1	0	0	0	0	0	0	1	0
Character number Reg.	0	0				(H _N -1)	Binary	,		

in the character display mode, H_N indicates the number of characters in the horizontal direction. In the graphic mode, it indicates the number of bytes in the horizontal direction. The total number of dots positioned horizontally on the screen n is given by the formula

$$n = Hp \times H_N$$

Even numbers in the range 2 to 256 (decimal) can be set as H_N.



4)Setting the time division number (display duty)

Reg	gister	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction	on Reg.	0	1	0	0	0	0	0	0	1	1
Time	division	0	0				(Nx-1)	Binary	,		
Reg.											

Consequently, 1/Nx is the display duty.

Decimal numbers with the range 1 to 256 can be set as Nx. please set Nx=64

5)Setting the cursor position

Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg.	0	1	0	0	0	0	0	1	0	0
Cursor position Reg.	0	0	0	0	0	0		(Cp-1)	Binary	,

In the character display mode, Cp indicates the line at which the cursor is displayed. For example, when Cp=8 (decimal) is specified, the cursor is displayed beneath the character of the 5×7 dot-font. The horizontal length of the cursor equals Hp (the horizontal character pitch). Decimal values in the range 1 to 16 can be assigned to Cp. When the value is less than the vertical character pitch $Vp(Cp \le Vp)$, display priority is given to the cursor (provided the cursor display is ON). The cursor is not displayed when CP> Vp. The horizontal length of the cursor equals Hp.

6)Setting the display start lower address

Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg.	0	7	0	0	0	0	1	0	0	0
Display start address Reg.	0	0		(sta	art add	ress lo	wer by	rte) bin	ary	
(lower byte)										

7)Setting the display start upper address

Register	ſ	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	
Instruction R	eg.	0	1	0	0	0	0	1	0	0	1	
Display	start											
address	Reg.	0	0		(sta	art add	ress up	per by	/te) bin	ary		
(upper byte)				(**************************************								



This instruction writes the display start value in the display start address register. The display start address inn the RAM address at which data to be displayed at the leftmost position of the top line of the screen is stored. The start address consists of 16 bits (upper and lower).

8)Setting the cursor (lower) address (RAM read/write lower address)

Reg	jister	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instructio	n Reg.	0	1	0	0	0	0	1	0	1	0
Cursor	address										
counter	(lower	0	0		(cur	sor ad	dress I	ower b	yte) bi	nary	
byte)									.500		

9)Setting the cursor (upper) address (RAM read/write upper address)

Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg.	0	1	0	0	0	0	1	0	1	1
Cursor address counter (upper byte)	0	0		(cur	sor add	dress u	ipper b	yte) bi	nary	

This instruction writes the cursor address value in the cursor address counter. The cursor address indicates the address for exchanging display data and character codes with RAM. In other words, data at the address specified by the cursor address is read from or written into RAM. In character display, the cursor is displayed at the position specified by the cursor address.

The cursor address is divided into a lower address (8 bits) and an upper address (8 bits). It should be set in accordance with the following rules.

1	To rewrite (set) both lower and upper addresses.	First set the lower address, then the upper.
2	To rewrite the lower address:	Always reset the upper address after setting the lower address.
3	To rewrite the upper address only:	Set the upper address. It is necessary to reset the lower address.

The cursor address counter is a 16-bit up-counter with set/reset functions: when the Nth bit goes from 1 to 0, the count of the (N+1)th bit increments by one. Accordingly, when the lower address is set so that the lower MSB (8th bit) changes from 1 to 0, the LSB (1st bit) of the upper counter must increment by one. When setting the cursor address, set the lower and upper addresses as a 2-byte continuous instruction.



10)Writing display data

Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg.	0	1	0	0	0	0	1	1	0	0
RAM	0	0	MS	B (patt	ern da	ta, cha	racter	code)		LSB

Write code "0CH" in the instruction register. Then, write 8-bit data with RS=0, and the data is written into RAM as display data or character codes at the address specified by the cursor address counter. After writing, the count of the cursor address counter increments by 1.

11)Reading display data

									W Y	
Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
-							4. Y		gala-	
Instruction Reg.	0	1	0	0	0	0	1	1	0	1
								A Comment		
RAM	1	0	MS	B (patt	ern da	ta, cha	racter	code)		LSB

Write "0DH" in the instruction register. Then, establish the read status with RS=0, and data in the RAM can be read. The procedure for reading data is as follows.

This instruction outputs the contents of the data output register to DB0 to 7, then transfers the RAM data indicated by the cursor address to the data output register. It then increments the cursor address by 1, which means that correct data cannot be read in the first read operation. The specified value is output in the second read operation. Accordingly, a dummy read operation must be performed once when reading data after setting the cursor address.

12)Bit clear

Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg.	0	1	0	0	0	0	1	1	1	0
Bit clear	0	0	0	0	0	0	0	(N _B	-1) Bin	ary



13)Bit set

Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
register	1 (/ / / /	110	יטט	סטט	סטט	דטט	סטט	DUL	יטטי	סטט
Instruction Reg	0	1	0	0	0	0	1	1	1	1
Bit set	0	0	0	0	0	0	0	(N _B	-1) Bin	ary

As the bit-clear or bit-set instruction, 1 bit of a 1 byte of data in display RAM is set to 0 or 1. The bit specified by N_B is set to 0 for the bit-clear instruction and 1 for the bit-set instruction. The RAM address is specified by the cursor address, which is automatically incremented by 1 at the completion of the instruction. NB is a value in the range from 1 to 8. The LSB is indicated by N_B =1, and the MSB by N_B =8.

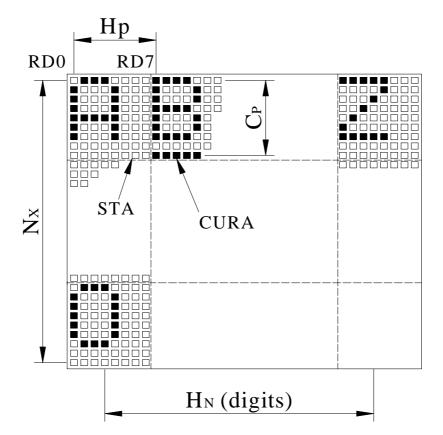
14)Reading the BUSY flag

Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
busy flag	1	1	1/0				*			

The Busy flag is output to DB7 when read mode is established with RS=1. The Busy flag is set to 1 while any of the instructions 1) through 13) is being executed. It is set to 0 at the completion of the execution, allowing the next instruction to be accepted. No other instruction can be accepted when the Busy flag is 1. Accordingly, before writing an instruction and data, it is necessary to ensure that the Busy flag is 0. However, the next instruction can be executed without checking the Busy flag when the maximum read cycle time or the write cycle time has been exceeded after execution of the previous data read instruction or the data write instruction.

The Busy flag does not change when data is written into the instruction register (RS=1). Therefore, the Busy flag need not be checked immediately after writing data into the instruction register.

Spacification of the instruction register is unpercessive to read the Rusy flag





Symbol	Description	Contents	Value
H_P	Horizontal character pitch		6 to 8 dots
H _N	Number of characters in the horizontal direction	Number of characters (digits) per horizontal line or the number of words per line (graphic)	Even digits in the range 2 to 256
V _P	Vertical character pitch	character pitch in the vertical direction	1 to 16 dots
C _P	Cursor position	The line number at which the cursor is to be displayed	1 to 16 lines
N _X	Number of lines in the vertical direction	Display duty	1 to 256 lines

Note)

When the number of vertical dots on the screen is m and that of horizontal dots is n,

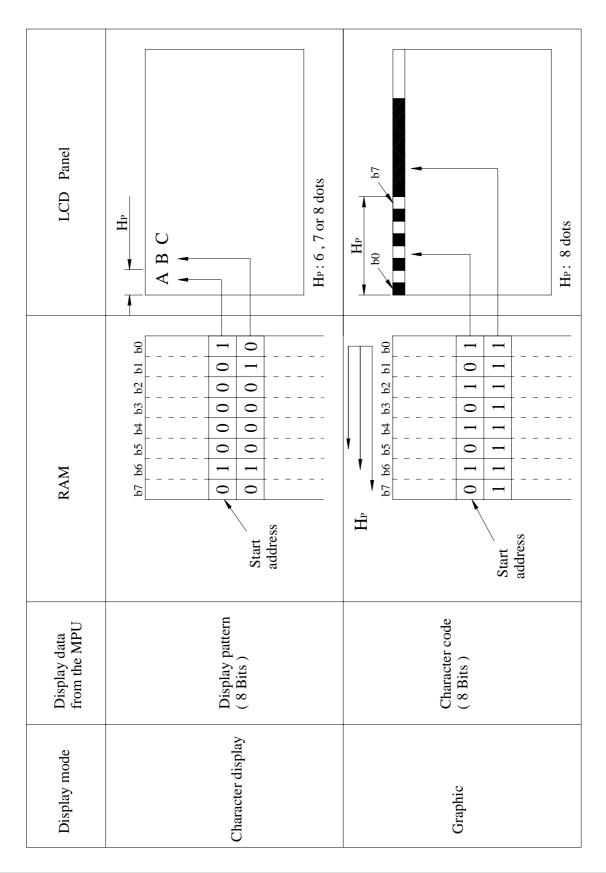
 $1/m = 1/N_X = display duty (nx=64)$

 $n=H_P \times H_N$

m/V_P= number of display lines, $C_P \le V_P$



Display mode





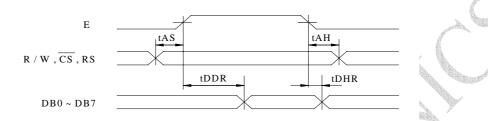
Built-in Chara

Upper 4 bit Lower	LLLL	LLLH	LLHL	LLHH	LHLL	LHLH	LHHL	LHHH	HLLL	HLLH	HLHL	НГНН	HHLL	HHLH	HHHL	нннн
4 bit																
LLLL						 :	•••							••••		
LLLH							-:::	-:::			:::		:::	···	-:::	
LLHL			::	•			i:	!··· ·			:	·‡.	•	.:: [:]	 	
LLHH				:	:	::	:				:	::::		•	:::	=:-:=
LHLL							::::	·i			•••					====
LHLH			:				::::				::				::::	ii
LHHL				::		i.,:		i.,:							<u></u>	=====
LHHH			:	:::			•	 i							·]	
HLLL			ŧ.	::		:.:: :::::	!··:	:::			·:i	·;		i,i	!"	:-::
HLLH				••	:	:::	:	••			•	•	.i		‡	·
HLHL			:	::	:		:						•	i	!	:::::
HLHH				::		i		•				:::	i		:-:	
HHLL			:	·:			<u>:</u>				-:	;	:	::::i	:::-	
HHLH							i i	:				:	•••	·· :		:
HHHL			::		! !	.•"•.	!":							•,••	! !	
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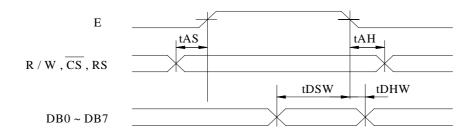


7. Timing Characteristics

Read cycle



Write cycle

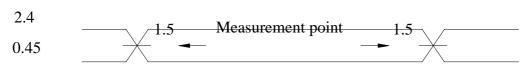


(Vss = 0 V, VDD = 5 V)

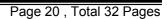
Item	Symbol	Min	Тур	Max	Unit
Address set-up time	tAS	90	_		ns
Address hold time	tAH	10	_		ns
Data delay time (read)	tDDR	_	_	140	ns
Data hold time (read)	tDHR	10	_	_	ns
Data set-up time (write)	tDSW	220	_	=	ns
Data hold time (write)	tDHW	20	_	_	ns



Note: Definition of the test waveform



The input terminals are driven at 2.4V and 0.45V. Timming is measured at 1.5V.

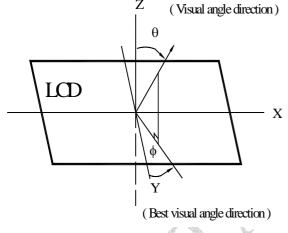




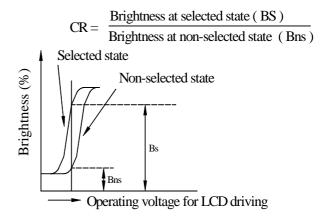
8. Optical Characteristics

ITEM	SYMBAL	CONDITION	MIN.	TYP.	MAX.	UNIT
	(V)θ	CR≧3	30	_	60	deg
View Angle	(Η)φ	CR≧3	-45	_	45	deg
Contrast Ratio	CR	_	_	5	_	
Response	T rise	_	_	200	300	ms
Time	T fall	_	_	200	300	ms

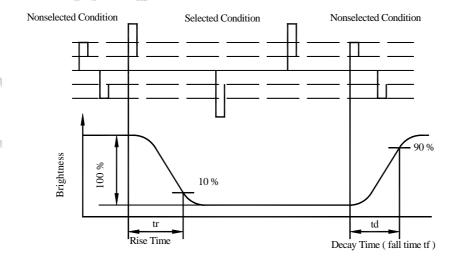
■View Angles



■Contrast Ratio



Resp





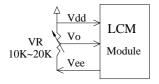
9. Absolute Maximum Ratings

ITEM	SYMBOL	MIN.	TYP.	MAX.	UNIT
Operating Temperature	T _{OP}	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T _{ST}	-30	_	+80	$^{\circ}\mathbb{C}$
Input Voltage	Vı	V _{SS}	_	V _{DD}	V
Supply Voltage For Logic	V _{DD} -V _{SS}	-0.3	_	47	V
Supply Voltage For LCD	V_{DD} - V_0	0	— "All	28	V

10. Electrical Characteristics

ITEM	SYMBOL	CONDITIO	MIN.	TYP.	MAX.	UNIT
Supply Voltage For Logic	V _{DD} -V _{SS}		4.75	5.0	5.25	V
Supply Voltage For		Ta=-20°ℂ	_	_	18.1	V
LCD *Note	V_{DD} - V_0	Ta=25°ℂ	_	16.3	_	V
		Ta=70°C	14.8	—	_	V
Input High Volt.	V _{IH}		2.2	_	V_{DD}	V
Input Low Volt.	V_{IL}	_	0	_	0.8	V
Output High Volt.	V _{OH}	_	2.4		V_{DD}	V
Output Low Volt.	V_{OL}	_	0		0.4	V
Supply Current	I _{DD}	V _{DD} =5V	18	25	30	mA

^{*} Note: Please design the VOP adjustment circuit on customer's main board





11. Backlight Information

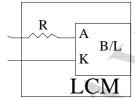
Specification

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	57.6	64	80	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	
Reverse Voltage	VR	_	_	5	V	
Luminous	IV	220	275		CD/M ²	ILED=64mA
Intensity		220	2/5		CD/IVI	ILED-04IIIA
Wave Length) n		X=0.30		nm /	ILED=64mA
wave Length	λρ		Y=0.31		nm	ILED-04IIIA
LED Life Time						ILED≦64mA
(For Reference only)	_	_	50K		Hr.	25℃,50-60%RH, (Note 1)
Color	White	1			e e	<u> </u>

Note:

The LED of B/L is drive by current only; drive voltage is for reference only. Drive voltage has to make driving current under safety area (current between minimum and maximum).

.Drive from pin19,pin20





12. Reliability

Content of Reliability Test (wide temperature, -20°c~70°C)

Environmental Test								
Test Item	Content of Test	Condition	Note					
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 200hrs	2					
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30℃ 200hrs	1,2					
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs	-					
Low Temperature Operation	temperature for a long time.	-20℃ 200hrs	1					
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60℃,90%RH 96hrs	1,2					
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20℃/70℃ 10 cycles	-					
Vibration test	Endurance test applying the vibration during transportation and using.	fixed amplitude: 15mm Vibration. Frequency: 10~55Hz. One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3					
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS= 1.5kΩ CS=100pF 1 time						

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



13. Inspection specification

NO	Item			Criterion		AQL		
01	Electrical Testing	defect. 1.2 Missing cha 1.3 Display mal 1.4 No function 1.5 Current con 1.6 LCD viewing 1.7 Mixed produ	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 					
02	Black or white spots on LCD (display only)	than three w	2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm					
03	LCD black spots, white spots, contaminatio	3.1 Round type Φ=(x + y) /		wing drawing		2.5		
	n (non-display)	3.2 Line type : ((As follow Length $$ $L \le 3.0$ $L \le 2.5$ $$	ing drawing) Width W≦0.02 0.02 <w≦0.03 0.03<w≦0.05="" 0.05<w<="" td=""><td>Acceptable Q TY Accept no dense 2 As round type</td><td>2.5</td></w≦0.03>	Acceptable Q TY Accept no dense 2 As round type	2.5		
04	Polarizer bubbles	If bubbles are vigudge using blaspecifications, reasy to find, mucheck in specify direction.	ck spot not ust	Size Φ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5		



NO	Item		Criterion		AQL
05	Scratches	Follow NO.3 LCD blace		contamination	
		Symbols Define: x: Chip length y k: Seal width t L: Electrode pad length 6.1 General glass chip 6.1.1 Chip on panel s	/: Chip width z: C : Glass thickness a: th: p :	hip thickness LCD side length	
06	Chipped glass	z: Chip thickness $Z \le 1/2t$ $1/2t < z \le 2t$ ① If there are 2 or mo $6.1.2 \text{ Corner crack:}$	y: Chip width Not over viewing area Not exceed 1/3k re chips, x is total leng	x: Chip length x≤1/8a x≤1/8a gth of each chip.	2.5
		z: Chip thickness Z≦1/2t 1/2t <z≦2t 2="" are="" if="" mo<="" or="" td="" there="" ⊙=""><td>y: Chip width Not over viewing area Not exceed 1/3k re chips, x is the total</td><td>x: Chip length x≤1/8a x≤1/8a length of each chip.</td><td></td></z≦2t>	y: Chip width Not over viewing area Not exceed 1/3k re chips, x is the total	x: Chip length x≤1/8a x≤1/8a length of each chip.	



NO	Item	Criterion	AQL
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:	
		$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	
06	Glass crack	y Z Z X X X X	2.5
		y: Chip width x: Chip length z: Chip thickness $y \le L$ $x \le 1/8a$ $0 < z \le t$ Olf the chipped area touches the ITO terminal, over 2/3 of the	
		ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack.	
		$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	



NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB 	2.5 2.5 0.65 2.5 0.65 2.5 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65



NO	Item	Criterion	AQL
12	General appearance	 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet. 	2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65

14. Precautions in use of LCD Modules

- 1. Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- 2. Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- 3. Don't disassemble the LCM.
- 4. Don't operate it above the absolute maximum rating.
- 5. Don't drop, bend or twist LCM.
- 6. Soldering: only to the I/O terminals.
- 7. Storage: please storage in anti-static electricity container and clean environment.
- 8. Raystar have the right to change the passive components (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- 9. Raystar have the right to change the PCB Rev.



15. Material List of Components for RoHs

1. RAYSTAR Optronics Co., Ltd. hereby declares that all of or part of products, including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS						

2. Process for RoHS requirement:

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow: 250°C, 30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°€;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.

16. Recommendable storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module



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		raye. i					
LCM Sample Estimate Feedback Sheet							
Module Number:							
1 · Panel Specification :							
1. Panel Type :	□ Pass	□ NG ,					
2. View Direction:	□ Pass	□ NG ,					
3. Numbers of Dots:	□ Pass	□ NG ,					
4. View Area:	□ Pass	□ NG ,					
5. Active Area:	□ Pass	□ NG ,					
6.Operating	□ Pass	□ NG ,					
Temperature :							
7.Storage Temperature:	□ Pass	□ NG ,					
8.Others:							
2 · Mechanical Specification	n:						
1. PCB Size:	□ Pass	□ NG ,					
2.Frame Size :	□ Pass	□ NG ,					
3.Materal of Frame:	□ Pass	□ NG ,					
4.Connector Position:	□ Pass	□ NG ,					
5.Fix Hole Position:	□ Pass	□ NG ,					
6.Backlight Position:	□ Pass	□ NG ,					
7. Thickness of PCB:	□ Pass	□ NG ,					
8. Height of Frame to	□ Pass	□ NG ,					
PCB:		4000000					
9.Height of Module:	□ Pass	□ NG ,					
10.Others:	□ Pass	□ NG ,					
3 · Relative Hole Size:							
1.Pitch of Connector:	□ Pass	□ NG ,					
2.Hole size of	□ Pass	□ NG ,					
Connector:	/						
3.Mounting Hole size	□ Pass	□ NG ,					
4.Mounting Hole Type:	□ Pass	□ NG ,					
5.Others:	□ Pass	□ NG ,					
4 · Backlight Specification :							
1.B/L Type:	□ Pass	□ NG ,					
2.B/L Color:	□ Pass	□ NG ,					
3.B/L Driving Voltage (Refe	erence for LI	ED Type) : □ Pass □ NG ,					
4.B/L Driving Current:	□ Pass	□ NG ,					
5.Brightness of B/L:	□ Pass	□ NG ,					
6.B/L Solder Method:	□ Pass	□ NG ,					
7.Others:	□ Pass	□ NG ,					

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Module Number :								
5 · Electronic Characteristics of Module :								
1.Input Voltage:	□ Pass	□ NG ,						
2.Supply Current:	□ Pass	□ NG ,						
3.Driving Voltage for LCD:	□ Pass	□ NG ,						
4.Contrast for LCD:	□ Pass	□ NG ,						
5.B/L Driving Method:	□ Pass	□ NG ,						
6.Negative Voltage	□ Pass	□ NG ,						
Output:								
7.Interface Function :	□ Pass	□ NG ,						
8.LCD Uniformity:	□ Pass	□ NG ,						
9.ESD test:	□ Pass	□ NG ,						
	□ Pass	□ NG ,						
10.Others: Pass NG, 6 · Summary:								
Sales signature:								
Customer Signature : <u>Date : / / </u>								